



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN192401A

Date: July 08, 2019

Subject: Addendum to PCN192401 - Qualification of Nitto EM-760 Die Attach Film and Die Thickness Change for 44-Lead TSOP II 2-Die Stack Packages Assembled at OSE-Taiwan

To: FUTURE ELECTRONICS
FUTURE ELE
pcn.system@futureelectronics.com

Change Type: Major

Description of Change:

The purpose of this addendum is to update the affected parts list communicated in the initial PCN192401.

Cypress announced the qualification of Nitto EM-760 Die Attach Film and die thickness change for 44-Lead TSOP II 2-Die Stack Pb Free Packages Assembled at OSE Taiwan.

This new die attach material is compatible with industry standard reflow conditions for applicable package volume, thickness and lead finish. There is no change in the moisture sensitivity level, product performance or ordering part numbers.

The 44-Lead TSOP II 2-Die Stack, 400 Mils, Pb-Free packages are assembled at OSE Taiwan using the following Bill of Materials:

Material	New OSE Taiwan BOM	Current OSE Taiwan BOM
Mold Compound	Hitachi CEL 9200HF-U	Hitachi CEL 9200HF-U
Leadframe	Cu Lead Frame	Cu Lead Frame
Die Attach Material	Nitto EM760	Hitachi HR5104
Bond Wire	1.0mil Au wire	1.0mil Au wire
Die thickness	3 mils	4 mils

Benefit of Change:

The qualification of the Nitto EM-760 die attach film and die thickness change allows for an improvement in product reliability and/or product cycle time.

Part Numbers Affected: 25

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:

This change has been qualified through a series of tests documented in the Qualification Test Plan QTP#190802. This qualification report can be found as an attachment to this PCN or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Sample Status:

Qualification samples may not be built ahead of time for all part numbers affected by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated OSE-Taiwan sample ordering part numbers. Samples are available now unless there is an indication that the sample ordering part numbers are subject to lead times. If you require qualification samples, please contact your local Cypress sales representative as soon as possible, preferably within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:

Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of Commercial, Industrial and Automotive non-PPAP part numbers in the attached file will be assembled at OSE-Taiwan or other approved assembly sites.

Anticipated Impact:

Products assembled with the Nitto EM-760 die attach film and new die thickness are completely compatible with existing products from form, fit, functional, parametric and quality performance perspectives.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Item	Marketing Part Number	Sample Order Part Number	Remarks
1	CY14B108K-ZS25XI	CY14B108K-ZS25XIKOO; Subject to lead time	
2	CY14B108K-ZS25XIT	CY14B108K-ZS25XIKOO; Subject to lead time	
3	CY14B108K-ZS45XI	CY14B108K-ZS45XIKOO	
4	CY14B108K-ZS45XIT	CY14B108K-ZS45XIKOO	
5	CY14B108L-ZS20XI	CY14B108L-ZS20XIKOO; Subject to lead time	
6	CY14B108L-ZS20XIT	CY14B108L-ZS20XIKOO; Subject to lead time	
7	CY14B108L-ZS25XI	CY14B108L-ZS25XIKOO; Subject to lead time	
8	CY14B108L-ZS25XIT	CY14B108L-ZS25XIKOO; Subject to lead time	
9	CY14B108L-ZS45XI	CY14B108L-ZS45XIKOO; Subject to lead time	
10	CY14B108L-ZS45XIT	CY14B108L-ZS45XIKOO; Subject to lead time	
11	CY7C1051DV33-10ZSXI	CY7C1051DV33-10ZSXIKO; Subject to lead time	Added in PCN192401A
12	CY7C1051DV33-10ZSXIT	CY7C1051DV33-10ZSXIKO; Subject to lead time	Added in PCN192401A
13	CY7C1051DV33-12ZSXI	CY7C1051DV33-12ZSXIKO; Subject to lead time	Added in PCN192401A
14	CY7C1051DV33-12ZSXIT	CY7C1051DV33-12ZSXIKO; Subject to lead time	Added in PCN192401A
15	CY7C1059DV33-10ZSXI	CY7C1059DV33-10ZSXIKO; Subject to lead time	Added in PCN192401A
16	CY7C1059DV33-10ZSXIT	CY7C1059DV33-10ZSXIKO; Subject to lead time	Added in PCN192401A
17	CY7C1059DV33-12ZSXQ	CY7C1059DV33-12ZSXQKO; Subject to lead time	Added in PCN192401A
18	CY7C1059DV33-12ZSXQT	CY7C1059DV33-12ZSXQKO; Subject to lead time	Added in PCN192401A
19	CYATB108LD-ZS45XI	CYATB108LD-ZS45XIKO; Subject to lead time	Added in PCN192401A
20	CG7480AT	CG7480ZT; Subject to lead time	Added in PCN192401A
21	CG7480ATT	CG7480ZT; Subject to lead time	Added in PCN192401A
22	CG8254AA	CG8254ZA; Subject to lead time	Added in PCN192401A
23	CG8836AMT	CG8836ZMT; Subject to lead time	Added in PCN192401A
24	CG8975AM	CG8975ZM; Subject to lead time	Added in PCN192401A
25	CG8975AMT	CG8975ZM; Subject to lead time	Added in PCN192401A



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

IPC Web Site for Information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type *

Declaration Class *

Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	Response Date *	Response Document ID				
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *					
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *		Supplier Comments or URL for Additional Information			
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
Alternate Recommendation				Alternate Item Comments				

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
			C	seconds	

Comments

Save the fields in this form to a file

Import fields from a file into this form

Clear all of the fields on this form

Lock the fields on this form to prevent changes

RoHS Material Composition Declaration

Declaration Type *

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

RoHS Declaration *

Supplier Acceptance *

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

